IPC ASSOCIATION ELECTRONIC	© Copyright 2005	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved un international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ls and Mfg I	nformati	on	
uppliei	r Information														
ompany	name*	Company unique ID			Ţ	Unique ID Authority					Response Date*				
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	Requester Item Number Mfr Ite		m Number Mfr Item Name				Effective Date	Versio	n	Manufacturing Site		Wei	ght*	UOM	Unit Type
		FDPF035N06B-F154 FET 60V 3.5 mOhm		nm TO220F		2025-06-07	5-06-07 CP8			1604	1.75	mg	Each		
lanufa	cturing Process Inform		Terminal Base	Alloy	-STD-020 MS	I. Doting	Dook Proc	ang Pady	Tamparatu	ro Moy Timo	at Dook T	Comporatura	Numb	er of Reflow Cyc	Jac
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or more	information regarding materi	al composition	nlease refer to	nage 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
irective 2015/863/EU amending RoHS irective 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier has provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	13.5	mg	Supplier	Silicon (Si)	7440-21-3		13.5	mg
Die Attach	12.0	mg	Supplier	Silver (Ag)	7440-22-4		0.18	mg
			A	Lead (Pb)	7439-92-1	7a	11.22	mg
			Supplier	Tin (Sn)	7440-31-5		0.6	mg
Lead Frame	519.74	mg	В	Nickel (Ni)	7440-02-0		0.052	mg
			Supplier	Iron (Fe)	7439-89-6		0.52	mg
			Supplier	Copper (Cu)	7440-50-8		518.9988	mg
			Supplier	Phosphorus (P)	7723-14-0		0.169	mg
Mold Compound-Black	1049.51	mg		Phenolic Resin	proprietary data		52.4755	mg
			Supplier	Carbon Black (C)	1333-86-4		5.2476	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		57.723	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		73.4657	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		73.4657	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		787.1325	mg
Plating	5.0	mg	Supplier	Tin (Sn)	7440-31-5		5	mg
Wire Bond - Al	5.0	mg	Supplier	Aluminum (Al)	7429-90-5		5	mg